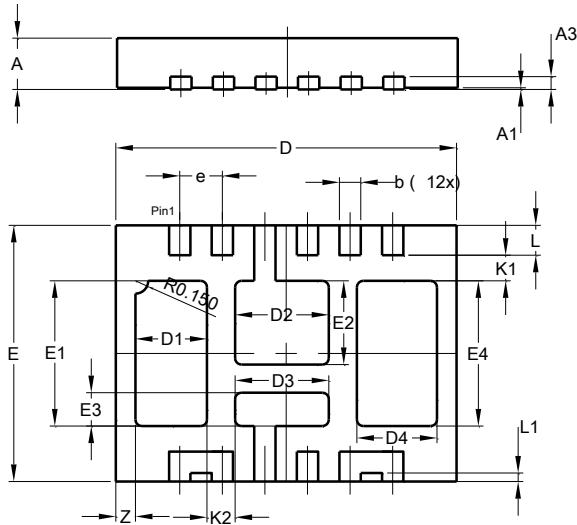


Package Outline Dimensions

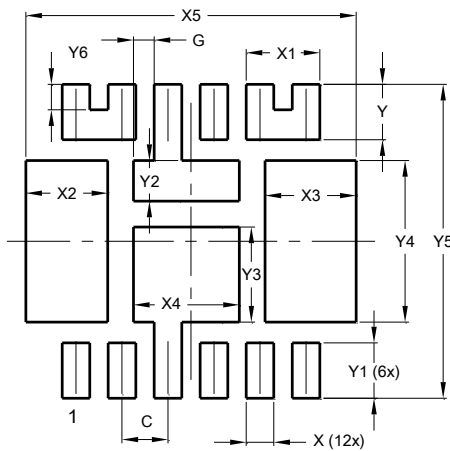
U-DFN4030-12 (Type C)



U-DFN4030-12 Type C							
Dim	Min	Max	Typ	Dim	Min	Max	Typ
A	0.57	0.63	0.60	E1	1.60	1.80	1.70
A1	0	0.05	0.02	E2	0.88	1.08	0.98
A3	-	-	0.015	E3	0.29	0.49	0.39
B	0.20	0.30	0.25	E4	1.60	1.80	1.70
D	3.95	4.05	4.00	e	-	-	0.50
D1	0.74	0.94	0.84	L	0.30	0.40	0.35
D2	1.00	1.20	1.10	L1	0.05	0.15	0.10
D3	1.00	1.20	1.10	K1	-	-	0.30
D4	0.84	1.04	0.94	K2	-	-	0.33
E	2.95	3.05	3.00	Z	-	-	0.23
All Dimensions in mm							

Suggested Pad Layout

U-DFN4030-12 (Type C)



Dimensions	Value (in mm)
C	0.500
G	0.225
X	0.300
X1	0.800
X2	0.890
X3	0.990
X4	1.150
X5	3.590
Y	0.600
Y1	0.600
Y2	0.440
Y3	1.030
Y4	1.750
Y5	3.400
Y6	0.275

ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS

Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.